

line 15, replace the word "firstly", with --first--.

On page 7, line 6, after "consistent", delete "to";

line 7, after "surfaces", insert --and--;

line 23, replace the word "present" with --prevent--.

On page 8, line 11, replace the word "solver" with --silver--;

line 21, replace the word "ration" with --ratio--.

On page 10, line 3, after the words "displacement plating process" insert -- often also

referred to as an electroplating process, --;

line 6, replace the word "protect" with --protected--.

On page 11, line 5, replace the word "solver" with --silver--.

**IN THE CLAIMS:**

Please amend the claims as follows:

1. (Amended) A process for [forming a silver coating on a surface of a metal which is less electropositive than silver comprising contacting the metal surface with an aqueous displacement plating composition comprising silver ions and a multidentate complexing agent in solution in an aqueous vehicle and having a pH of from 2 to 12, to form a coating of silver on the metal surface] providing a protective coating on metal conducting surfaces of bare boards in the manufacture of printed circuit boards, comprising the steps of contacting the conducting surfaces with an aqueous displacement plating composition which comprises silver ions and a multidentate complexing agent in solution in an aqueous vehicle at a pH of from 2 to 12 to form a silver coating on the conducting surfaces.